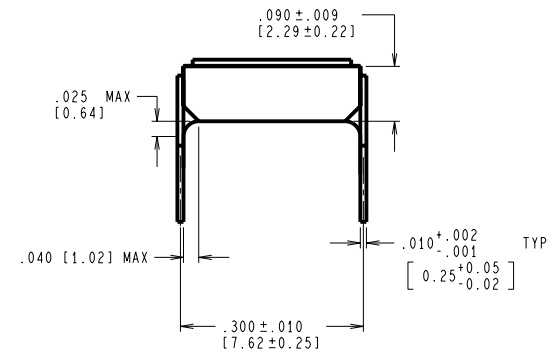
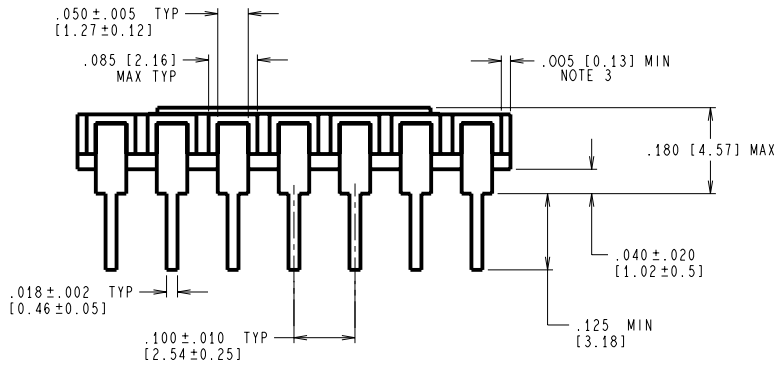
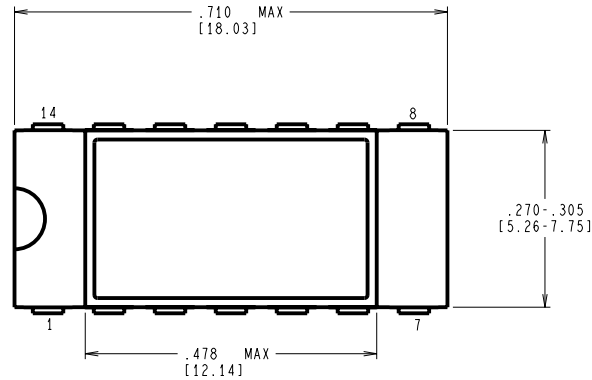


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
H	REVISE AND REDRAW PER NEW STANDARD.	10257	02/08/94	DEG/TP
J	.085 MAX WAS .080 ± .008; .270-.305 WAS .290-.003.	10474	06/30/94	DEG/



NOTES: UNLESS OTHERWISE SPECIFIED.

- LEAD FINISH TO BE ONE OF THE FOLLOWING:
 - 200 MICROINCHES/5.08 MICROMETERS MINIMUM SOLDER MEASURED AT THE CREST OF THE MAJOR FLATS.
 - 50 MICROINCHES/1.27 MICROMETERS MINIMUM GOLD OVER 50 TO 350 MICROINCHES/1.27 TO 8.89 MICROMETERS NICKEL UNDERPLATE.
- LEAD FINISH, NICKEL UNDERPLATE AND BASIS METAL SHALL CONFORM TO THE REQUIREMENTS OF MIL-M-38510.
- DIMENSION .005 IN/0.13mm MINIMUM SHALL BE MEASURED FROM THE EDGE OF THE FURTHEST EXTENSION OF THE METAL PAD OR LEAD.
- REFERENCE JEDEC REGISTRATION MS-015, VARIATION AB, DATED 7/90.

CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

MIL-M-38510
CONFIGURATION CONTROL

MIL/AERO
CONFIGURATION CONTROL

APPROVALS		DATE	NATIONAL SEMICONDUCTOR CORPORATION		
DRAWN	<i>Dwayne Grady</i>	02/08/94	2900 Semiconductor Drive, Santa Clara, CA 95052-8090		
DTG. CHK.			DIP, SIDEBRAZED CERAMIC, 14 LEAD		
ENGR. CHK.					
APPROVAL					
PROJECTION		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	MKT-D14D	J
INCH [MM]		DO NOT SCALE DRAWING			SHEET 1 of 1